

SVxx25xxQ Series

25 Amp High Junction Temperature SCRs



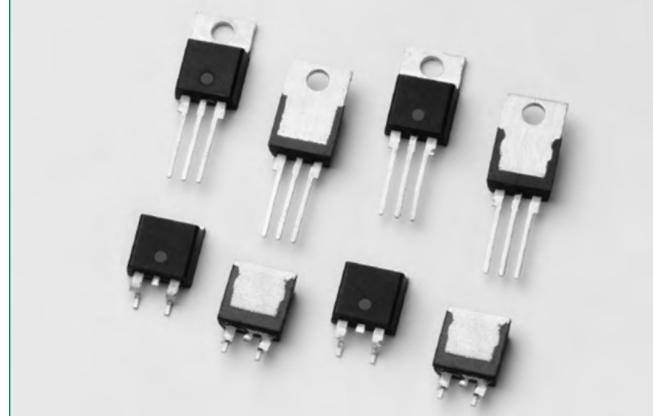
Description

The SVxx25xxQ high temperature SCR series is ideal for uni-directional switch applications such as phase control in heating, motor speed controls, converters/rectifiers and inrush current controllers.

These SCRs have a low gate current, (IGT) trigger level of 6mA and 10mA maximum at approximately 1.5V for SVxx25x1Q and SVxx25x2Q, respectively.

Features & Benefits

- Halogen free and RoHS compliant
- 150°C maximum junction temperature
- High dv/dt performance
- Low turn off time
- Electrically isolated
“L - Package” is UL 1557 recognized for 2500 VRMS
- Surge capability up to 350 A at 60 Hz half cycle



Additional Information



Resources



Accessories



Samples

Applications

Typical applications include AC Generator (ACG) rectifiers, battery voltage regulators, generic converters, inrush current controller in various AC to DC applications and soft starter for low power AC motor. Additional applications include controls for power tools, home/brown good and white goods appliances.

Internally constructed isolated packages offered for ease of heat sinking with high isolation voltage.

Agency Approval

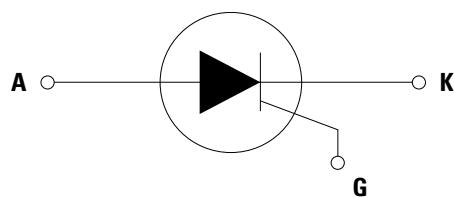
Agency	Agency File Number
	E71639*

* - L Package Only

Main Features

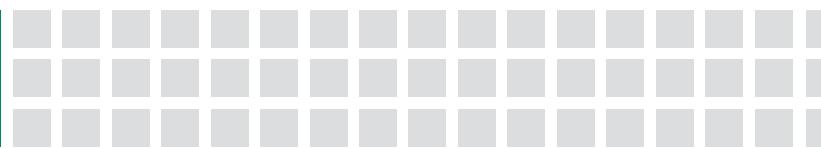
Symbol	Value	Unit
$I_{T(RMS)}$	25	A
V_{DRM}/V_{RRM}	600	V
I_{GT}	6 to 10	mA

Schematic Symbol



SVxx25xxQ Series

25 Amp High Junction Temperature SCRs



Absolute Maximum Ratings

Symbol	Parameter	Test Conditions		Value	Unit
V_{DSM}/V_{RSM}	Peak non-repetitive blocking voltage	$P_W = 100 \mu s$		800	V
$I_{T(RMS)}$	RMS on-state current	SVxx25LxQ	$T_c = 100^\circ C$	25	A
		SVxx25RxQ SVxx25NxQ	$T_c = 125^\circ C$		
$I_{T(AV)}$	Average on-state current	SVxx25LxQ	$T_c = 100^\circ C$	16	A
		SVxx25RxQ SVxx25NxQ	$T_c = 125^\circ C$		
I_{TSM}	Peak non-repetitive surge current	single half cycle; $f = 50\text{Hz}$; T_J (initial) = $25^\circ C$		300	A
		single half cycle; $f = 60\text{Hz}$; T_J (initial) = $25^\circ C$		350	
I^2t	I^2t Value for fusing	$t_p = 8.3 \text{ ms}$		510	A^2s
dI/dt	Critical rate of rise of on-state current	$f = 60\text{Hz}; T_J = 150^\circ C$		125	$\text{A}/\mu\text{s}$
I_{GM}	Peak gate current	$T_J = 150^\circ C$		4	A
$P_{G(AV)}$	Average gate power dissipation	$T_J = 150^\circ C$		0.8	W
T_{stg}	Storage temperature range			-40 to 150	$^\circ C$
T_J	Operating junction temperature range			-40 to 150	$^\circ C$

Note: xx=voltage/10, x=sensitivity

Electrical Characteristics ($T_J = 25^\circ C$, unless otherwise specified)

Symbol	Test Conditions	SVxx25x1Q	SVxx25x2Q	Unit
I_{GT}	$V_D = 12\text{V}$ $R_L = 60 \Omega$	MAX.	6	mA
		MIN.	2	
V_{GT}	$V_D = 12\text{V}$ $R_L = 60 \Omega$	MAX.	1.5	V
dv/dt	$V_D = 67\% V_{DRM}$; gate open; $T_J = 125^\circ C$	400	800	$\text{V}/\mu\text{s}$
	$V_D = 67\% V_{DRM}$; gate open; $T_J = 150^\circ C$	200	400	
V_{GD}	$V_D = V_{DRM}$ $R_L = 3.3 \text{ k}\Omega$ $T_J = 150^\circ C$	MIN.	0.2	V
I_H	$I_T = 400\text{mA}$ (initial)	MAX.	25	mA
t_q	$I_T = 2\text{A}$; $t_p = 50\mu\text{s}$; $dv/dt = 5\text{V}/\mu\text{s}$; $di/dt = 30\text{A}/\mu\text{s}$	MAX.	12	μs
t_{gt}	$I_G = 2 \times I_{GT}$ $P_W = 15\mu\text{s}$ $I_T = 50\text{A}$	TYP.	2.6	μs

Note: xx=voltage/10, x=package

Static Characteristics

Symbol	Test Conditions	Value	Unit
V_{TM}	$I_T = 50\text{A}$; $t_p = 380 \mu\text{s}$	1.7	V
I_{DRM} / I_{RRM}	$V_{DRM} = V_{RRM}$	MAX.	μA
		10	
		1000	
		4000	

Thermal Resistances

Symbol	Parameter	Value	Unit
$R_{\Theta(JC)}$	Junction to case (AC)	1.3 2.5	$^\circ C/W$

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SVxx25xxQ Series

25 Amp High Junction Temperature SCRs

Figure 1:
Normalized DC Gate Trigger Current vs. Junction Temperature

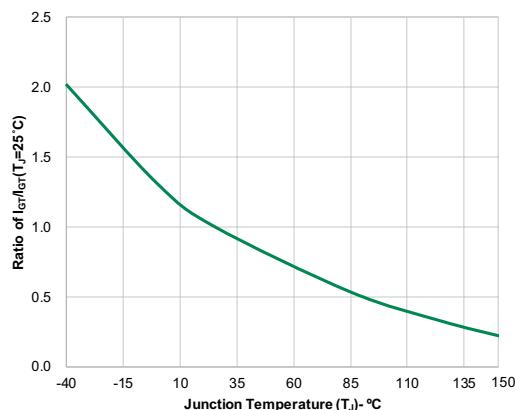


Figure 2:
Normalized DC Gate Trigger Voltage vs. Junction Temperature

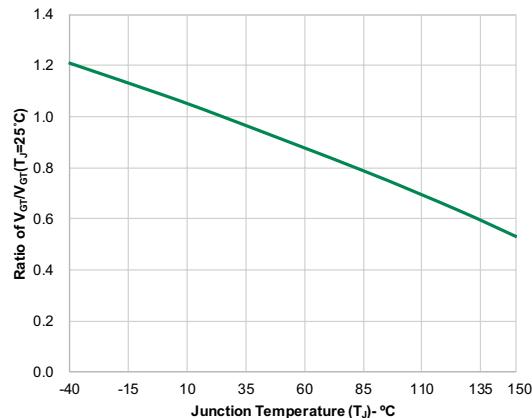


Figure 3:
Normalized DC Holding Current vs. Junction Temperature

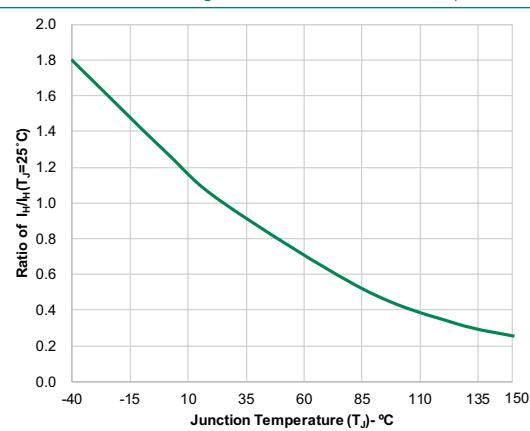


Figure 4:
On-State Current vs. On-State Voltage (Typical)

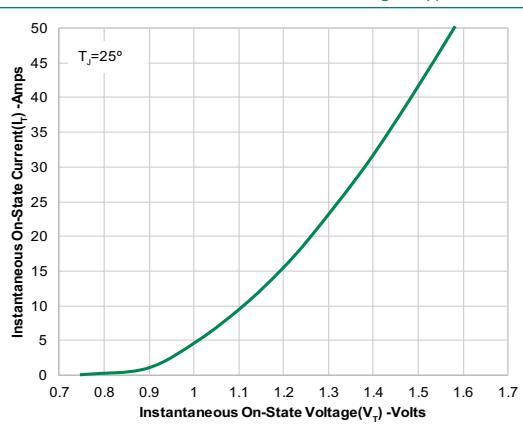


Figure 5:
Power Dissipation (Typical) vs. RMS On-State Current

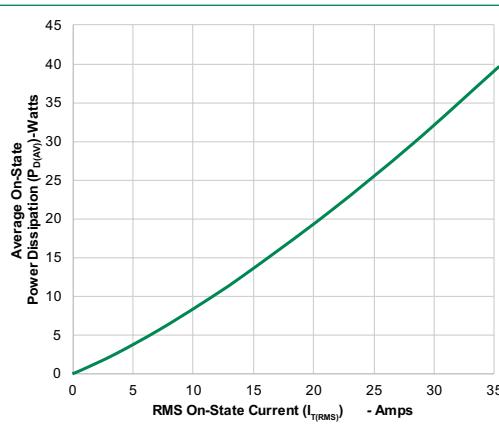
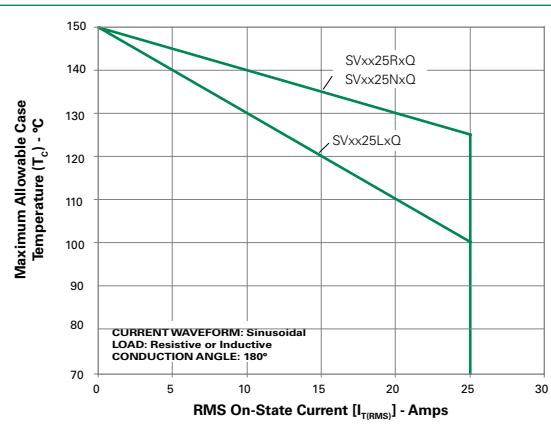


Figure 6:
Maximum Allowable Case Temperature vs. RMS On-State Current



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Figure 7:
Maximum Allowable Case Temperature
vs. Average On-State Current

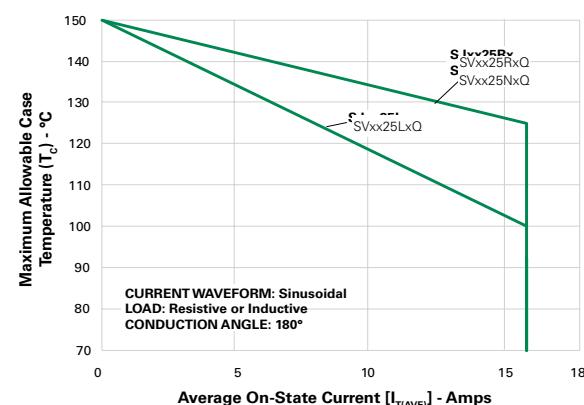


Figure 8:
Peak Capacitor Discharge Current

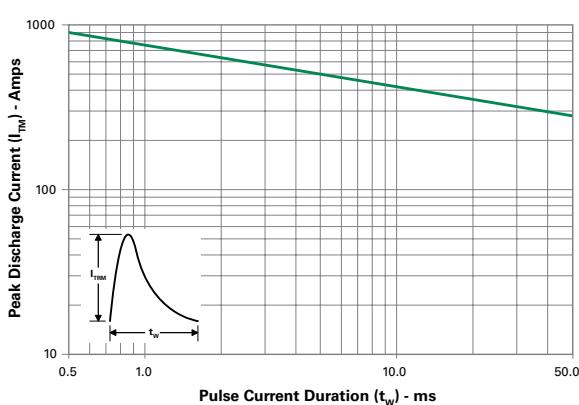
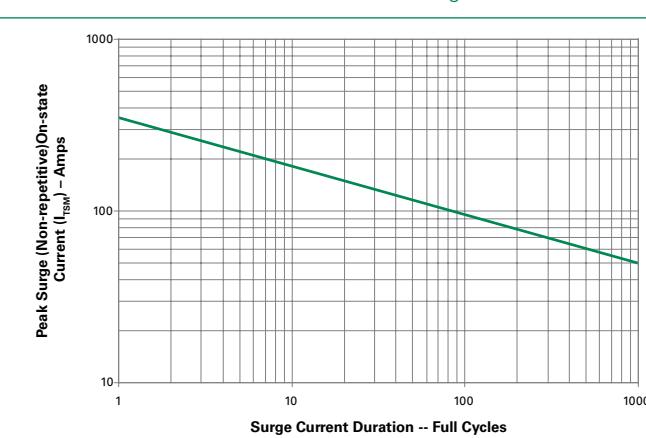


Figure 9:
Peak Capacitor Discharge Current Derating



Figure 10:
Surge Peak On-State Current vs. Number of Cycles



Supply Frequency: 60 Hz Sinusoidal
Load: Resistive
RMS On-State Current: $I_{T(RMS)}$: Maximum Rated Value at Specified Case Temperature

Notes:

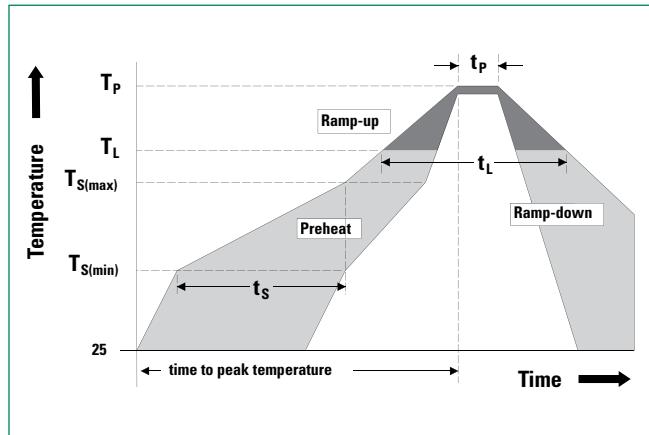
1. Gate control may be lost during and immediately following surge current interval.
2. Overload may not be repeated until junction temperature has returned to steady-state rated value.

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Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Time (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		280°C



Physical Specifications

Terminal Finish	100% Matte Tin-plated
Body Material	UL Recognized compound meeting flammability rating V-0
Lead Material	Copper Alloy

Design Considerations

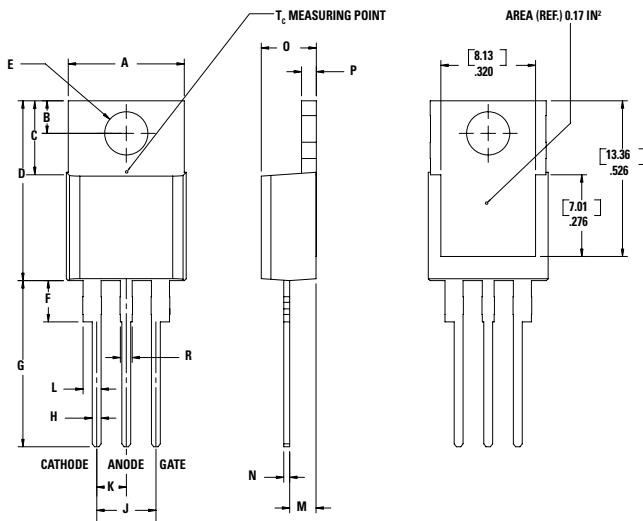
Careful selection of the correct component for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the component rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including dv/dt), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.

Environmental Specifications

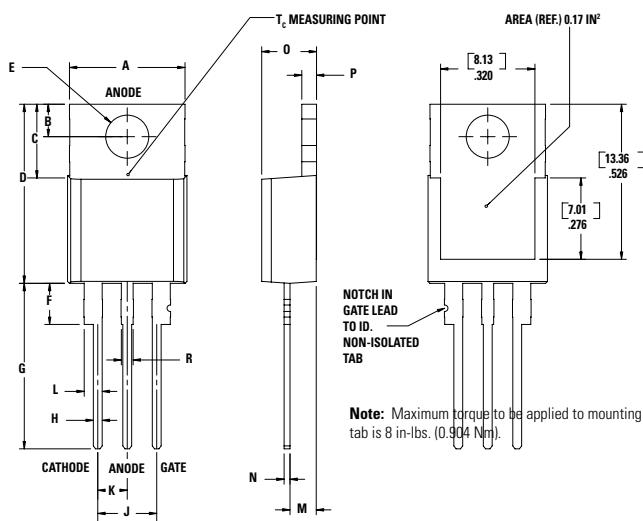
Test	Specifications and Conditions
AC Blocking	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 150°C for 1008 hours
Temperature Cycling	MIL-STD-750, M-1051, 1000 cycles; -55°C to +150°C; 15-min dwell-time
Temperature/Humidity	EIA / JEDEC, JESD22-A101 1008 hours; 160V - DC: 85°C; 85% rel humidity
Resistance to Solder Heat	MIL-STD-750 Method 2031
Solderability	ANSI/J-STD-002, category 3, Test A
Lead Bend	MIL-STD-750, M-2036 Cond E
Moisture Sensitivity Level	Level 1, JEDEC-J-STD-020D

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Dimensions — TO-220AB (L-Package) — Isolated Mounting Tab

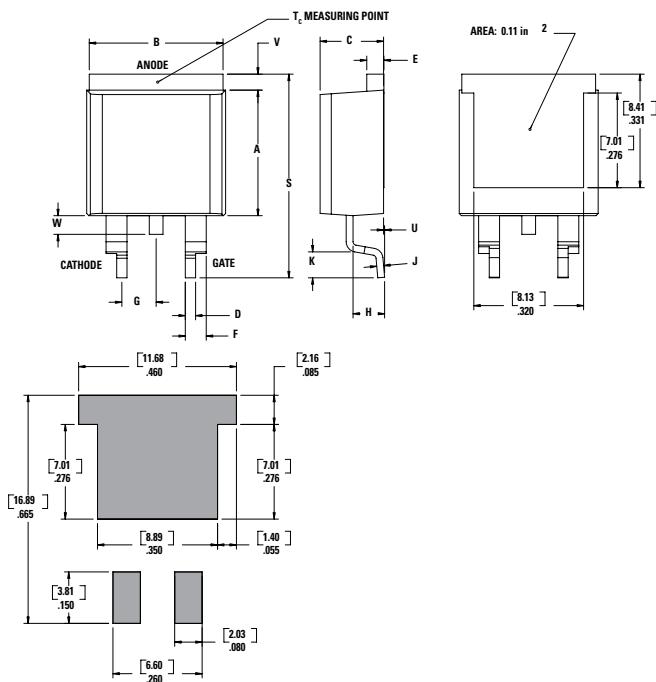
Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.97	1.22

Dimensions — TO-220AB (R-Package) — Non-Isolated Mounting Tab Common with Center Lead

Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.97	1.22

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Dimensions — TO- 263AB (N-package) — D2-Pak Surface Mount

Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.360	0.370	9.14	9.40
B	0.380	0.420	9.65	10.67
C	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
E	0.045	0.060	1.14	1.52
F	0.060	0.075	1.52	1.91
G	0.095	0.105	2.41	2.67
H	0.092	0.102	2.34	2.59
J	0.018	0.024	0.46	0.61
K	0.090	0.110	2.29	2.79
S	0.590	0.625	14.99	15.88
V	0.035	0.045	0.89	1.14
U	0.002	0.010	0.05	0.25
W	0.040	0.070	1.02	1.78

Product Selector

Part Number	Voltage 600V	Gate Sensitivity	Type	Package
SVxx25L1Q	X	6mA	Standard SCR	TO-220L
SVxx25R1Q	X	6mA	Standard SCR	TO-220R
SVxx25N1Q	X	6mA	Standard SCR	TO-263
SVxx25L2Q	X	10mA	Standard SCR	TO-220L
SVxx25R2Q	X	10mA	Standard SCR	TO-220R
SVxx25N2Q	X	10mA	Standard SCR	TO-263

Note: xx = Voltage/10, x=sensitivity

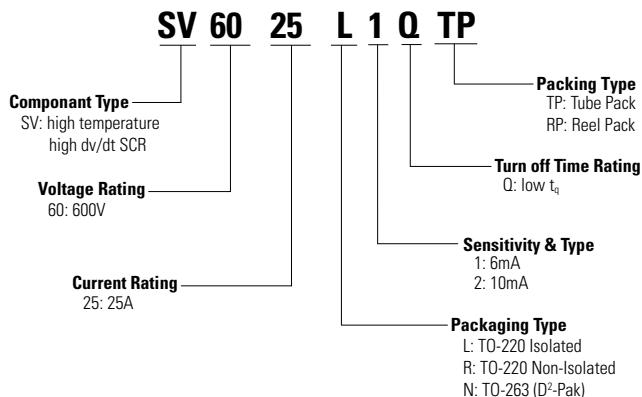
Packing Options

Part Number	Marking	Weight	Packing Mode	Base Quantity
SVxx25LxQTP	SVxx25LxQ	2.2g	Tube	1000 (50 per tube)
SVxx25RxQTP	SVxx25RxQ	2.2g	Tube	1000 (50 per tube)
SVxx25NxQTP	SVxx25NxQ	1.6g	Tube	1000 (50 per tube)
SVxx25NxQRP	SVxx25NxQ	1.6g	Embossed Carrier	500

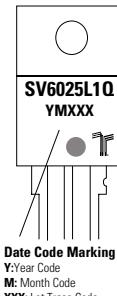
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Part Numbering System**Part Marking System**

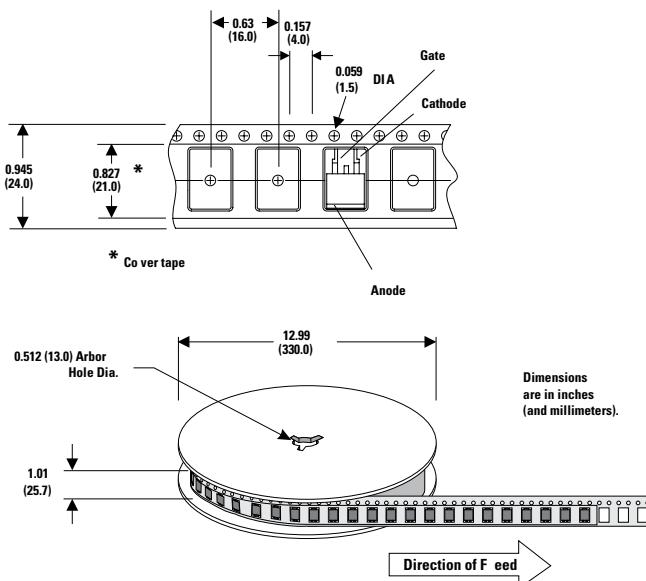
TO-220 AB - (L and R Package)
TO-263 AB - (N Package)



Date Code Marking
 Y: Year Code
 M: Month Code
 XXX: Lot Trace Code

TO-263 Embossed Carrier Reel Pack (RP) Specifications

Meets all EIA-481-2 Standards



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